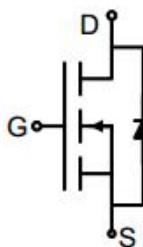
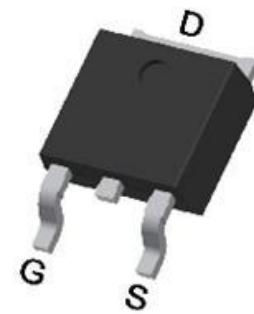


## N-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>The GT080N10K uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge. It can be used in a wide variety of applications.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}</math> 100V</li> <li>● <math>I_D</math> (at <math>V_{GS} = 10V</math>) 75A</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = 10V</math>) &lt; 8mΩ</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = 4.5V</math>) &lt; 10mΩ</li> <li>● 100% Avalanche Tested</li> <li>● RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Power switch</li> <li>● DC/DC converters</li> </ul>	 <p>Schematic Diagram</p>  <p>TO-252</p>		
<b>Device</b>	<b>Package</b>	<b>Marking</b>	<b>Packaging</b>
GT080N10K	TO-252	GT080N10	2500pcs/Reel

<b>Absolute Maximum Ratings</b> $T_C = 25^\circ\text{C}$ , unless otherwise noted			
<b>Parameter</b>	<b>Symbol</b>	<b>Value</b>	<b>Unit</b>
Drain-Source Voltage	$V_{DS}$	100	V
Continuous Drain Current	$I_D$	75	A
Pulsed Drain Current (note1)	$I_{DM}$	300	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Single Pulse Avalanche Energy (note2)	$E_{AS}$	132	mJ
Power Dissipation	$P_D$	100	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 150	$^\circ\text{C}$

<b>Thermal Resistance</b>			
<b>Parameter</b>	<b>Symbol</b>	<b>Value</b>	<b>Unit</b>
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	60	$^\circ\text{C/W}$
Maximum Junction-to-Case	$R_{thJC}$	1.25	$^\circ\text{C/W}$

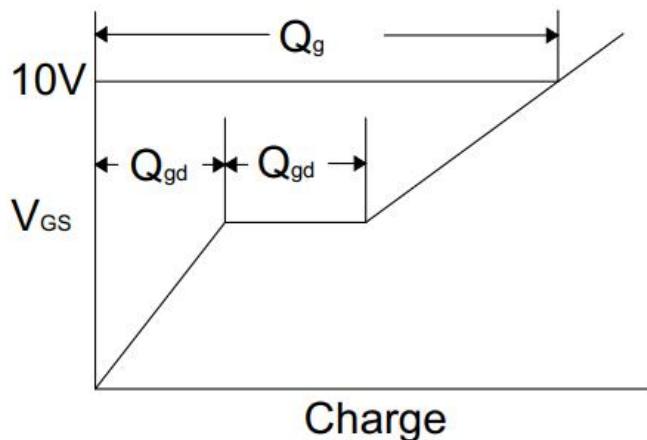
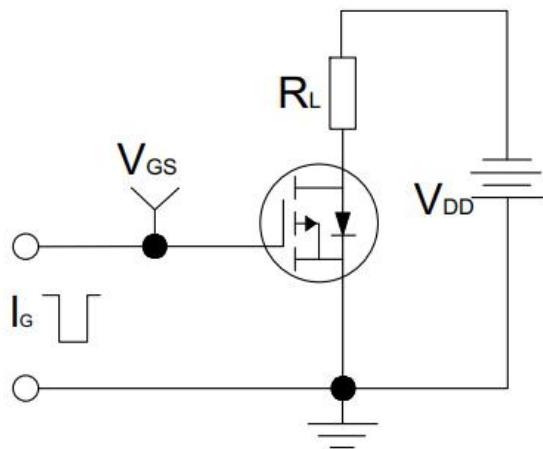
**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	100	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{DS} = 100V, V_{GS} = 0V$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{GS} = \pm 20V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.3	3	V
Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 50\text{A}$	--	6.5	8	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 50\text{A}$	--	8	10	
Forward Transconductance	$g_{\text{FS}}$	$V_{DS} = 5V, I_D = 50\text{A}$	--	70	--	s
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{GS} = 0V,$ $V_{DS} = 50V,$ $f = 1.0\text{MHz}$	--	2056	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	395	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	19	--	
Total Gate Charge	$Q_g$	$V_{DD} = 50V,$ $I_D = 40\text{A},$ $V_{GS} = 10V$	--	70	--	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		--	14.5	--	
Gate-Drain Charge	$Q_{gd}$		--	17	--	
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = 50V,$ $I_D = 40\text{A},$ $R_G = 1.6\Omega$	--	16	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	11	--	
Turn-off Delay Time	$t_{d(\text{off})}$		--	35	--	
Turn-off Fall Time	$t_f$		--	9	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source Current	$I_s$	$T_C = 25^\circ\text{C}$	--	--	75	A
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = 50\text{A}, V_{GS} = 0V$	--	--	1	V
Reverse Recovery Charge	$Q_{rr}$	$I_F = 20\text{A}, V_{GS} = 0V$ $di/dt=500\text{A}/\mu\text{s}$	--	880	--	$\text{nC}$
Reverse Recovery Time	$T_{rr}$		--	64	--	ns

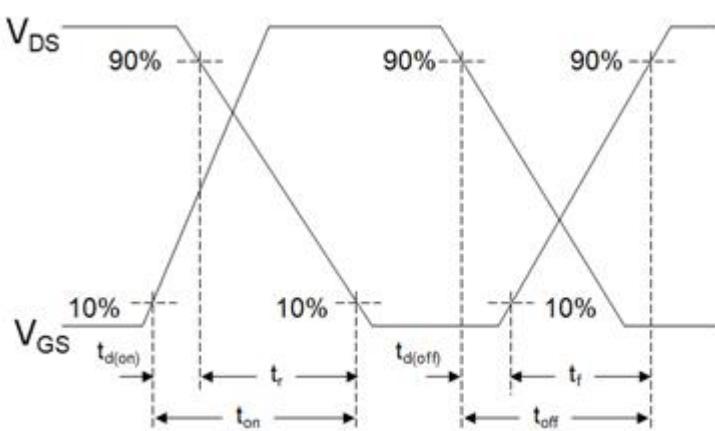
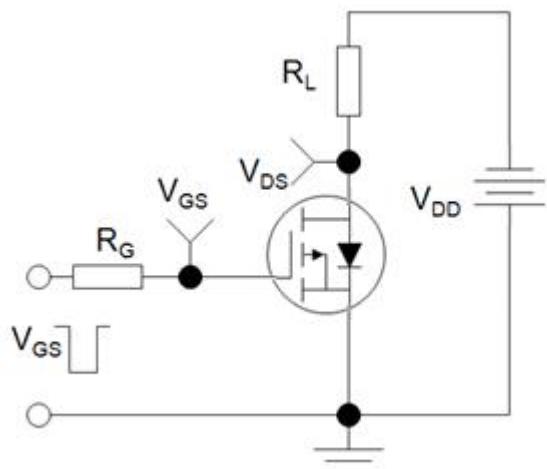
**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical  $R_G$
3. EAS condition :  $T_J=25^\circ\text{C}$ ,  $VDD=50V$ ,  $VGS=10V$ ,  $L=0.5\text{mH}$ ,  $Rg=25\Omega$

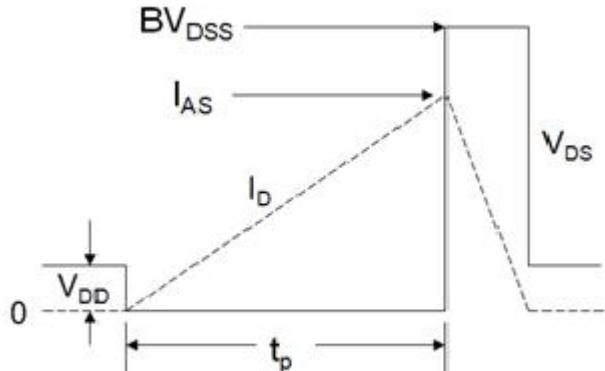
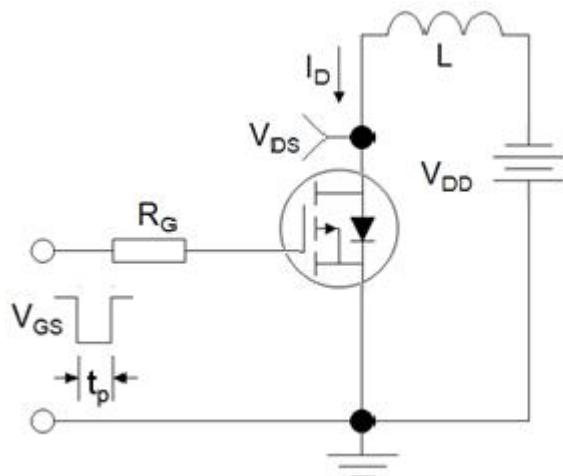
**Gate Charge Test Circuit**



**Switch Time Test Circuit**

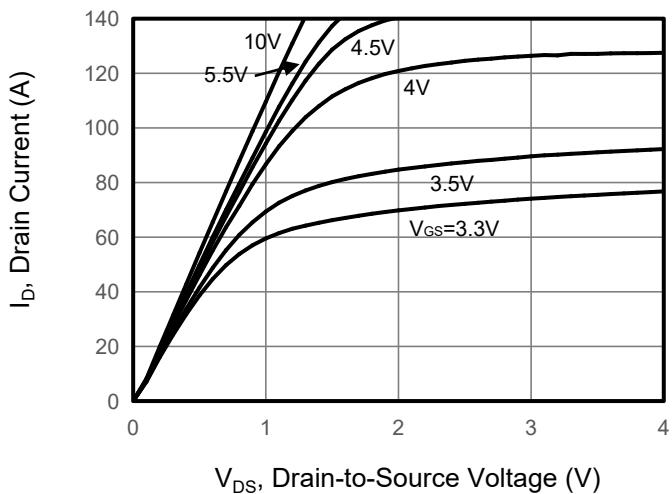


**EAS Test Circuit**

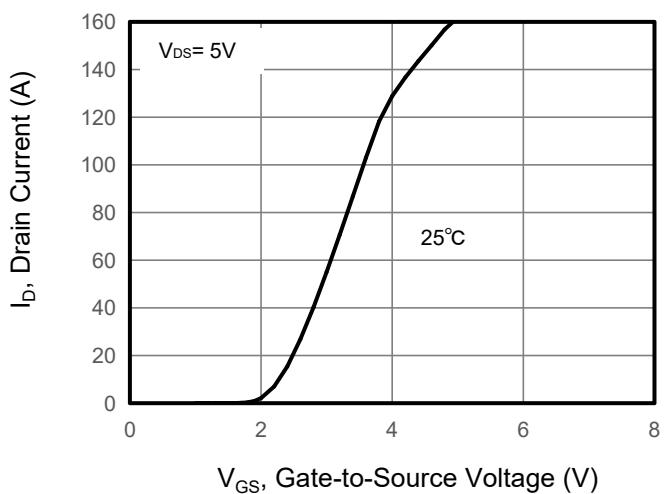


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

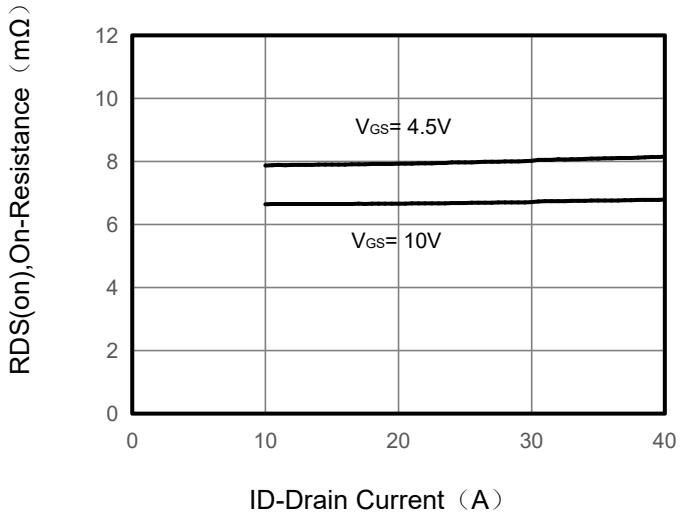
**Figure 1. Output Characteristics**



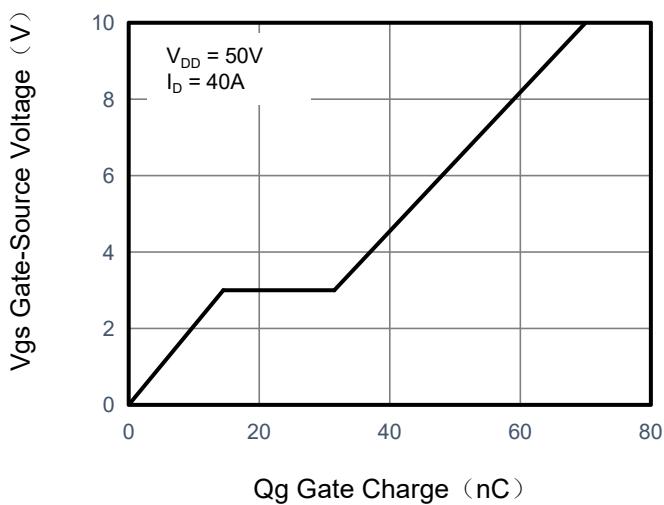
**Figure 2. Transfer Characteristics**



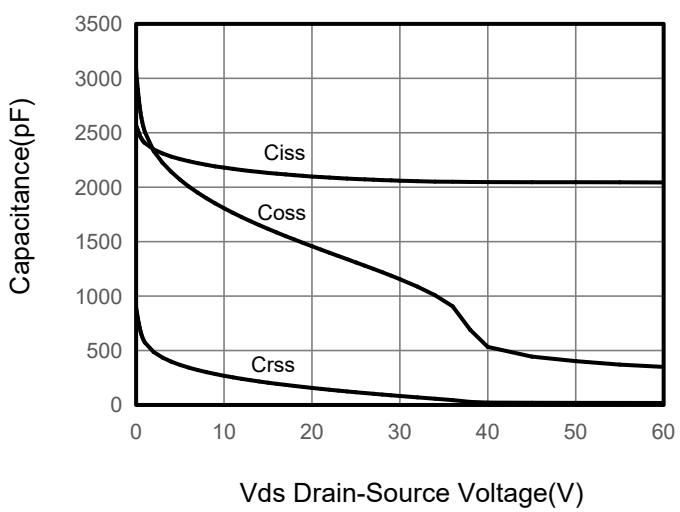
**Figure 3. Drain Source On Resistance**



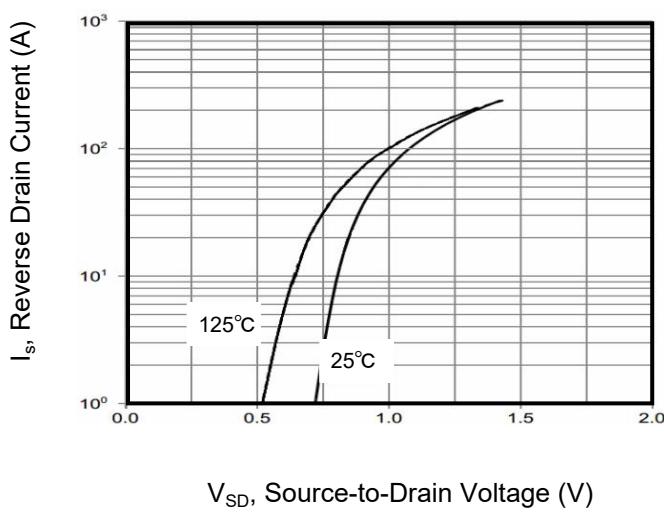
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

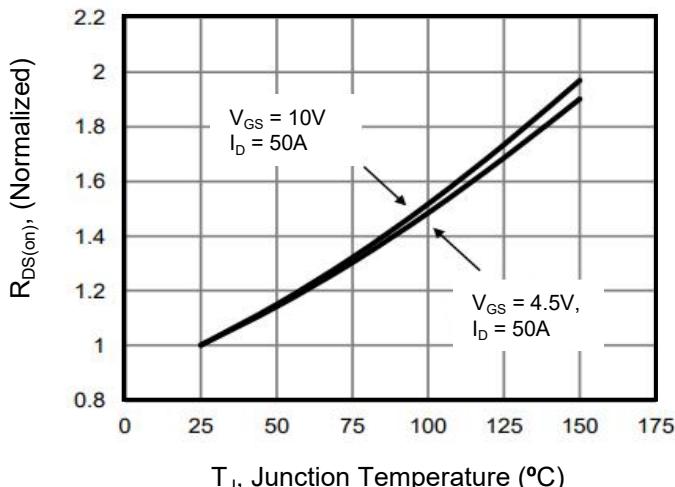


**Figure 6. Source-Drain Diode Forward**

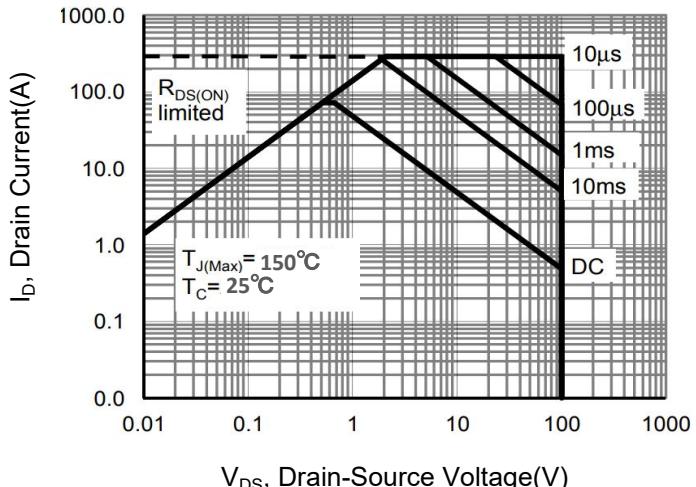


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

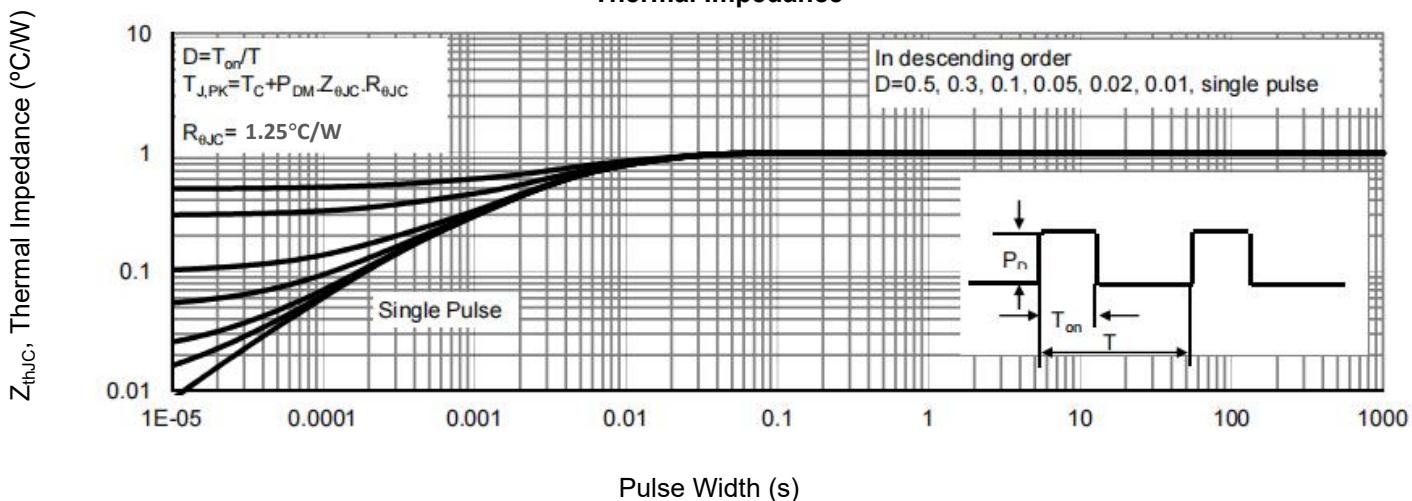
**Figure 7. Drain-Source On-Resistance**



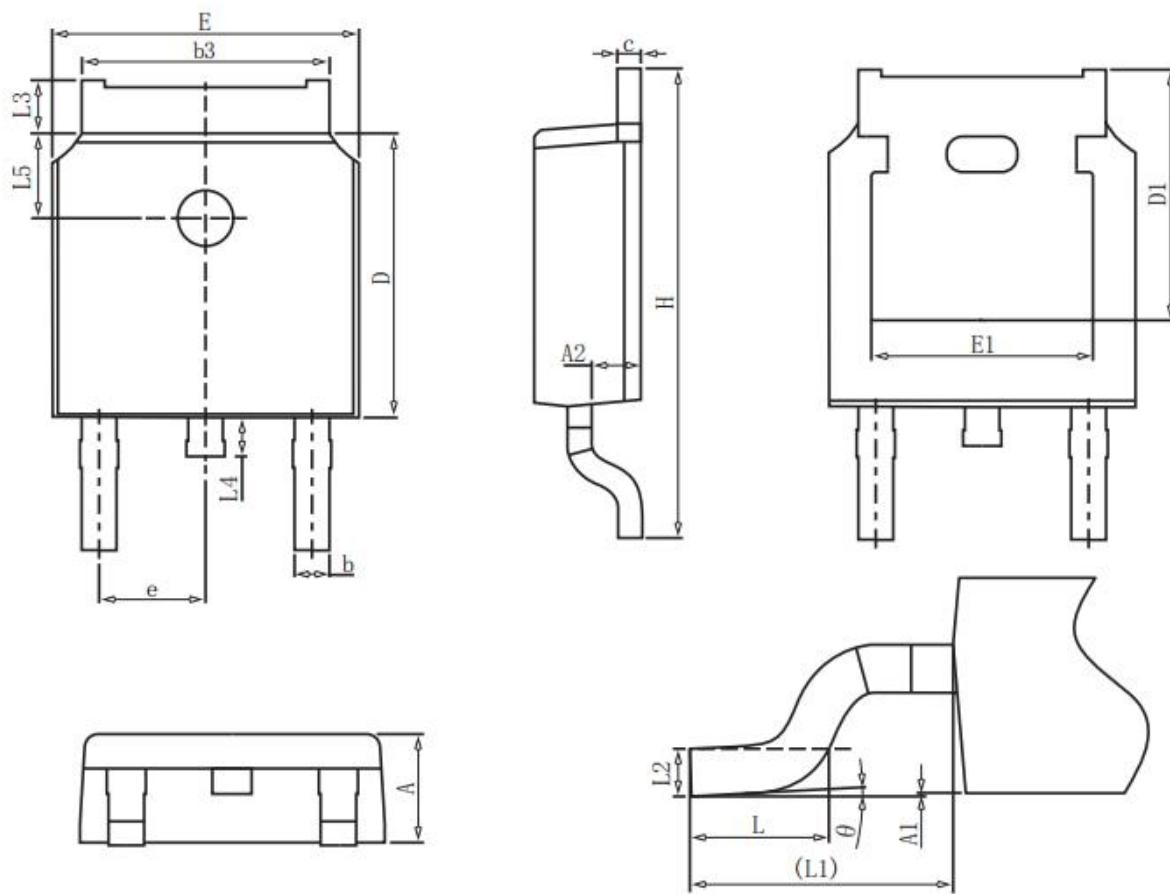
**Figure 8. Safe Operation Area**



**Figure 9. Normalized Maximum Transient Thermal Impedance**



## TO-252 Package Information



## COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1		5.30REF	
E	6.40	6.60	6.80
E1	4.63	-	-
e		2.286BSC	
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1		2.90REF	
L2		0.51BSC	
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°